Si4431CDY

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Vishay Siliconix

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PRODUCT SUMMARY					
V _{DS} (V)	-30				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.032				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -4.5 V	0.049				
Q _g typ. (nC)	13				
I _D (A) ^d	-9				
Configuration	Single				

FEATURES

P-Channel 30-V (D-S) MOSFET

- TrenchFET[®] power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Load switch
- · Battery switch



RoHS COMPLIANT HALOGEN FREE Available

Q _g typ. (nC)	13		D
I _D (A) ^d	-9	P-Channel M	
Configuration	Single	7	
ADDEDING INFADM			
ORDERING INFORM	ATION		
ORDERING INFORM Package	ATION	SO-8	
	ATION	SO-8 Si4431CDY-T1-E3	

ABSOLUTE MAXIMUM RATINGS (TA	= 25 °C, unless other	wise noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-30	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		-9		
	T _C = 70 °C	1 , [-7.2		
	T _A = 25 °C	I _D	-7 ^{a, b}		
	T _A = 70 °C	1	-5.6 ^{a, b}	А	
Pulsed drain current	I _{DM}	-30			
	T _C = 25 °C		-3.5		
Continuous source-drain diode current	T _A = 25 °C	I _S	-2.1 ^{a, b}	1	
	T _C = 25 °C		4.2		
Maximum names dissinction	T _C = 70 °C	1 5 6	2.7	14/	
Maximum power dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C	1 –	1.6 ^{a, b}	1	
Operating junction and storage temperature range	•	T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS PARAMETER S

PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient a, c	t ≤ 10 s	R _{thJA}	40	50	°C 4M
Maximum junction-to-foot	Steady state	R _{thJF}	24	30	°C/W

Notes

a. Surface mounted on 1" x 1" FR4 board

b. t = 10 s

c. Maximum under steady state conditions is 95 $^{\circ}\text{C/W}$

d. Based on T_C = 25 °C

S09-0322-Rev. B, 02-Mar-09

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Document Number: 68748



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	L 050	-	-31	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	4.5	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	-1	-	-2.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA	
Zave gete veltage ducin ovyment	1	V _{DS} = -30 V, V _{GS} = 0 V		-	-1		
Zero gate voltage drain current	IDSS	V_{DS} = -30 V, V_{GS} = 0 V, T_{J} = 55 °C	-	-	-5	-μΑ	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	-20	-	-	А	
During a summer and state unaristance a	D	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -7 \text{ A}$	-	0.026	0.032	- Ω	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5.6 \text{ A}$	-	0.037	0.049		
Forward transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -7 \text{ A}$	-	18	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	1006	-		
Output capacitance	C _{oss}	V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHz	-	180	-	pF	
Reverse transfer capacitance	C _{rss}		-	145	-		
	0	V_{DS} = -15 V, V_{GS} = -10 V, I_D = -7 A	-	25	38		
Total gate charge	e charge Q_g		-	13	20		
Gate-source charge	Q _{gs}	V_{DS} = -15 V, V_{GS} = -4.5 V, I_D = -7 A	-	3.5	-	nC	
Gate-drain charge	Q _{gd}		-	5.5	-	1	
Gate resistance	R _g	f = 1 MHz	0.4	2	4	Ω	
Turn-on delay time	t _{d(on)}		-	10	20		
Rise time	tr	V_{DD} = -15 V, R_L = 2.7 Ω	-	13	20	1	
Turn-off delay time	t _{d(off)}	$I_D\cong$ -5.6 A, V_{GEN} = -10 V, R_g = 1 Ω	-	23	35		
Fall time	t _f		-	9	18		
Turn-on delay time	t _{d(on)}		-	38	57	ns	
Rise time	t _r	V_{DD} = -15 V, R_L = 2.7 Ω	-	89	134		
Turn-off delay time	t _{d(off)}	$I_D\cong$ -5.6 A, V_{GEN} = -4.5 V, R_g = 1 Ω	-	22	33		
Fall time	t _f		-	11	17		
Drain-Source Body Diode Characteri	stics			•			
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-3.5	•	
Pulse diode forward current	I _{SM}		-	-	-30	A	
Body diode voltage	V _{SD}	$I_{\rm S}$ = -5.6 A, $V_{\rm GS}$ = 0 V	-	-0.71	-1.2	V	
Body diode reverse recovery time	t _{rr}		-	22	33	ns	
Body diode reverse recovery charge	Q _{rr}	I _F = -5.6 A, di/dt = 100 A/μs,	-	17	26	nC	
Reverse recovery fall time	ta	$T_J = 25 \text{ °C}$	-	13	-		
Reverse recovery rise time	t _b		-	9	_	ns	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

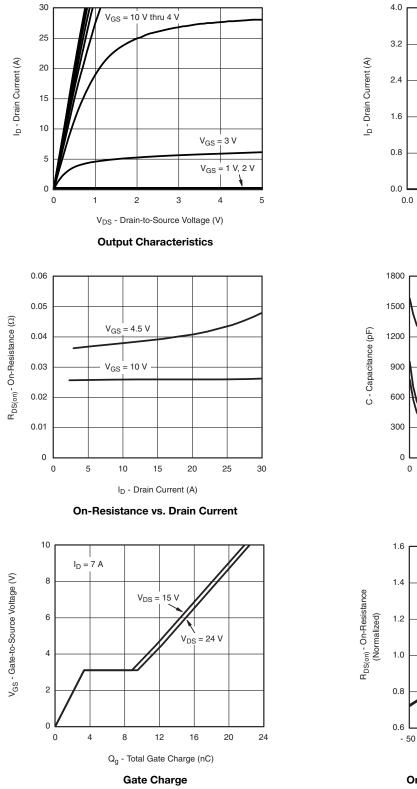
b. Guaranteed by design, not subject to production testing

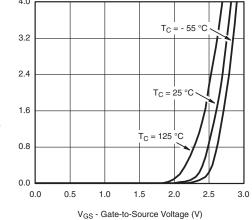
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2

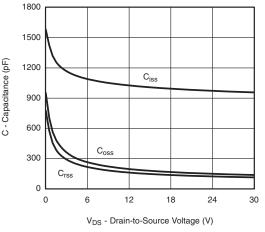


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

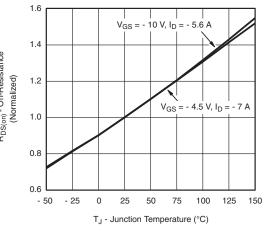




Transfer Characteristics







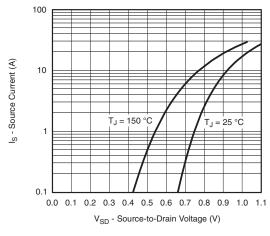
On-Resistance vs. Junction Temperature

3

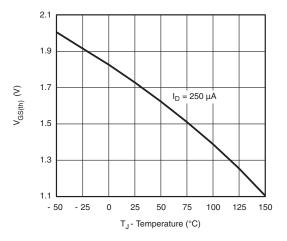
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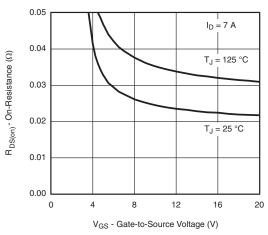
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



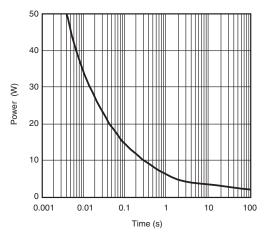
Source-Drain Diode Forward Voltage



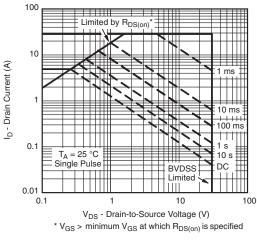




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



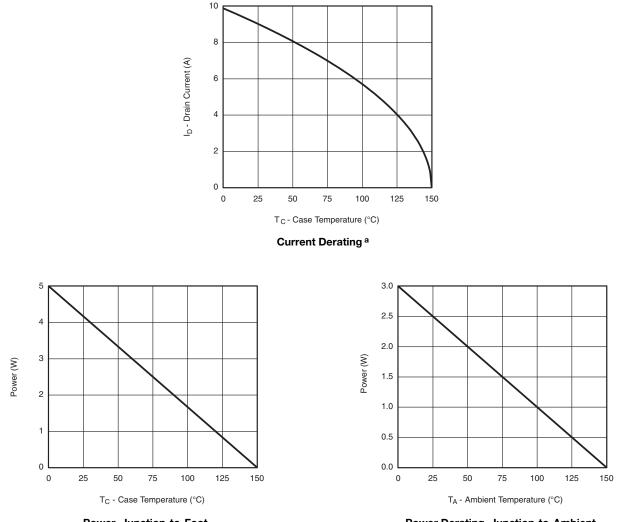
Safe Operating Area

4

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Power, Junction-to-Foot

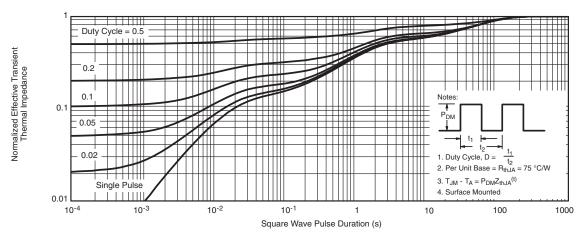


Note

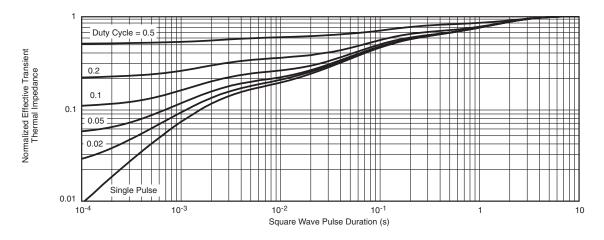
a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68748.

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Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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